客户图

NOTES:

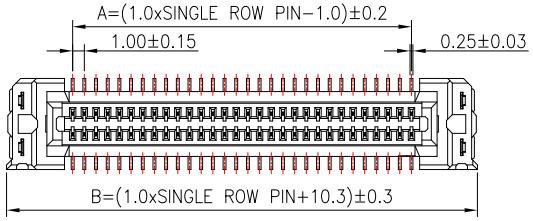
1. FINISH:
   - 1.1 HOUSING: POLYAMIDE BLACK,UL94V-0.
   - 1.2 CONTACT: PHOSPHOR BRONZE,GOLD (SEE P/N) PLATED IN CONTACT AERA, GOLD FLASH PLATED IN SOLDER AREA, 50u" MIN. NICKEL UNDERPLATED OVERALL.
   - 1.3 GROUND: BRASS,80u" MIN MATTE TIN PLATED OVER 50u" MIN NICKEL UNDERPLTAED OVERALL.
2. ELECTRICAL:
   - 2.1 CURRENT RATING: 0.5A/PIN
   - 2.2 VOLTAGE RATING: 125V AC/DC.
   - 2.3 CONTACT RESISTANCE: 65mΩ MAX.
   - 2.4 INSULATION RESISTANCE: 250V DC/0.1S/1000MΩ
3. Max Processing Temp:265°C Seconds 40S
4. FLOATING RANGE OF THIS CONNECTOR IS 0.7MM MAX. THE MAXIMUM CYCLE TIME OF THE FLOATING OPERATION IS IN ACCORDANCE WITH THE MATING CYCLE OF THE CONNECTOR
5. PLEASE USE THE CONNECTORS WITHIN THE SPECIFIED PCB DISTANCE. PLEASE REFER TO THE DRAWINGS OF MATING CONNECTOR
6. BLEMISH AND HIT MARK CAN BE OCCURED THROUGH OUT THE MANUFACTURING PROCESS
7. ORDER INFORMATION:

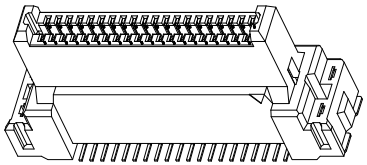
AA D6 M XXX XX XXX R 1

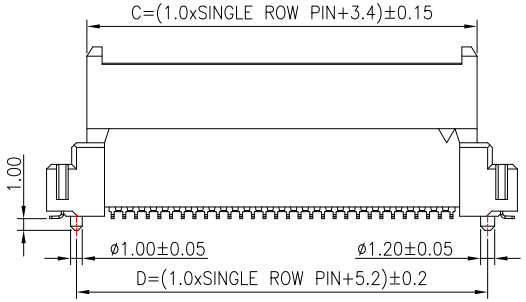
Pin数码	端子电镀：	塑胶高度：	包装方式：
060=2*30PIN	N0=Gold Flash/Ni（半金镍）	117=11.70mm ("G")	R=载带包装
……	N1=1u" Gold/Ni	147=14.70mm ("G")	
	N2=3u" Gold/Ni	167=16.70mm ("G")	
	N3=5u" Gold/Ni		
	N4=10u" Gold/Ni		
	N5=15u" Gold/Ni		
	N6=30u" Gold/Ni		

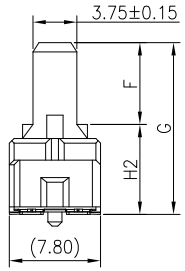
TABLE:

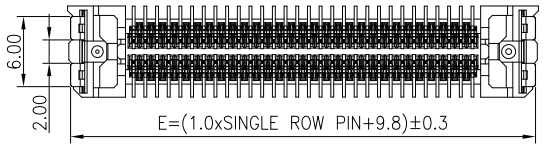
No. OF PIN	A	B	C	D	E
020=2x10PIN	9.00	20.30	13.40	15.20	19.80
030=2x15PIN	14.00	25.30	18.40	20.20	24.80
040=2x20PIN	19.00	30.30	23.40	25.20	29.80
050=2x25PIN	24.00	35.30	28.40	30.20	34.80
060=2x30PIN	29.00	40.30	33.40	35.20	39.80

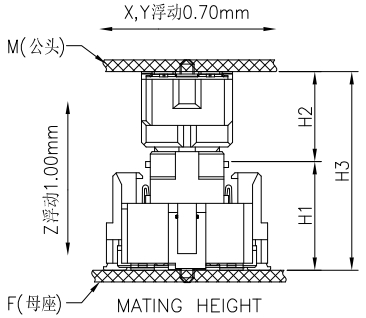


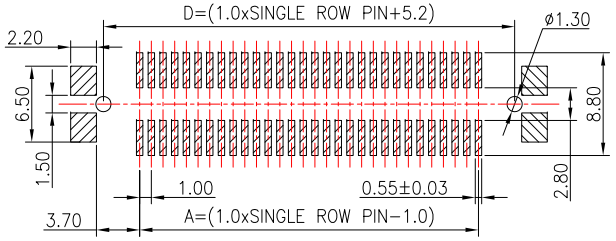












RECOMMENDED PCB LAYOUT
PCB BOARD TOLFRANCF±0.05

"G" STACK HEIGHT	H2	F
11.70mm	4.70	7.00
14.70mm	7.70	
16.70mm	9.70	

H1	H2	"H3" MATING HEIGHT
9.30	4.70	15.00
	7.70	18.00
	9.70	20.00
14.30	4.70	20.00
	7.70	23.00
	9.70	25.00

GENERAL TOLERANCES UNLESS SPECIFIED		PART NO.	CONSHARE
X.X	±0.30	AAD6MXXXXXXXXR1	
X.XX	±0.2	APPROVED BY	TITLE
X.XXX	±0.1	JACK	1.00mm 浮动BTB 公头直立式SMT TYPE
Angle	±3°	CHECKED BY	DWG NO.
DIM.	TOL	MIKE	
SIZE	UNITS	DRAWN BY	SHEET / SCALE / REV
A4	MM(INCH)	CC	1:1 / 1:1 / 0